







## **MIDEM 2021**

56<sup>th</sup> INTERNATIONAL CONFERENCE ON MICROELECTRONICS, DEVICES AND MATERIALS WITH THE WORKSHOP ON PERSONAL SENSOR FOR REMOTE HEALTH CARE MONITORING

September 22<sup>nd</sup> – September 24<sup>th</sup>, 2021 Faculty of Electrical Engineering, Ljubljana, Slovenia

# **Announcement and Call for Papers**

### **Chairs:**

Prof. dr. Janez Trontelj (UL FE) Doc. Dr. Aleksander Sešek (UL FE)

#### **IMPORTANT DATES**

Abstract submission deadline: May 1, 2021

Acceptance notification: June 15, 2021

Full paper submission deadline: July 31, 2021

Invited and accepted papers will be published in the Conference Proceedings.

Deatailed and updated information about the MIDEM Conferences, as well as for paper preparation can be found on

http://www.midem-drustvo.si/

#### GENERAL INFORMATION

The 56<sup>th</sup> International Conference on Microelectronics, Devices and Materials with the Workshop on Personal Sensor for Remote Health Care Monitoring continues a successful tradition of the annual international conferences organized by the MIDEM Society, the Society for Microelectronics, Electronic Components and Materials. The conference will be held at Faculty of Electrical Engineering, Ljubljana, Slovenia from SEPTEMBER 22<sup>nd</sup> – September 24<sup>th</sup>, 2021

### Topics of interest include but are not limited to:

- Workshop focus: Personal Sensor for Remote Health Care Monitoring,
- Novel monolithic and hybrid circuit processing techniques,
- New device and circuit design,
- Process and device modelling,
- Semiconductor physics,
- Sensors and actuators,
- Electromechanical devices, microsystems and nanosystems,
- Nanoelectronics,
- Optoelectronics,
- Photovoltaic devices,
- Electronic materials science and technology,
- New electronic materials and applications,
- Materials characterization techniques,
- Reliability and failure analysis,
- Education in microelectronics, devices and materials.

#### **ORGANIZER:**

MIDEM Society - Society for Microelectronics, Electronic Components and Materials, Slovenia

CONFERENCE SPONSORS: UL FE, UL FS, IJS, IMAPS, Slovenia Chapter; IEEE, Slovenia Section